

## 2.4GHz 1608 Chip Antenna: RANT1608F245C01



### Application:

WLAN, 802.11b/g, Bluetooth, WLAN, etc...

### Features

SMD, high reliability, ultra Impact, Omni-directional...

### Part number Information

RANT   1608   F   245   C   01  
(A)   (B)   (C)   (D)   (E)   (F)

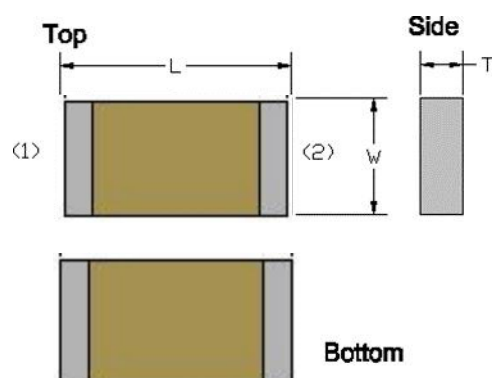
|                  |                       |
|------------------|-----------------------|
| (A)Product Type  | Chip Antenna          |
| (B) Size Code    | 1.6x0.8mm(±0.1mm)     |
| (C) Material     | High K material       |
| (D) Frequency    | 2.4 ~ 2.5GHz          |
| (E) Feeding mode | PIFA & Single Feeding |
| (F) Antenna type | Type=01               |

### Electrical Specification

|                               |                    |
|-------------------------------|--------------------|
| Working Frequency Range       | 2400 ~2500 MHz     |
| Bandwidth                     | 120 MHz (Min.)     |
| Peak Gain                     | 3.35 dBi (Typ.)    |
| Impedance                     | 50 Ohm             |
| Return loss                   | 10 dB ( Min)       |
| Polarization                  | Linear             |
| Azimuth Beamwidth             | Omni-directional   |
| Operation Temperature(°C)     | -40 ~85°C          |
| Resistance to Soldering Heats | 10sec. ( @ 280°C)  |
| Termination                   | Ni / Au (Leadless) |

The specification is defined on EVB.

### Dimension and Terminal Configuration



| Dimension (mm) |             |
|----------------|-------------|
| L              | 1.60 ± 0.10 |
| W              | 0.80 ± 0.10 |
| T              | 0.80 ± 0.10 |

| No. | Terminal Name |
|-----|---------------|
| 1   | Feeding/GNG   |
| 2   | GND/Feeding   |

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RAIN International Technology Co., Ltd.

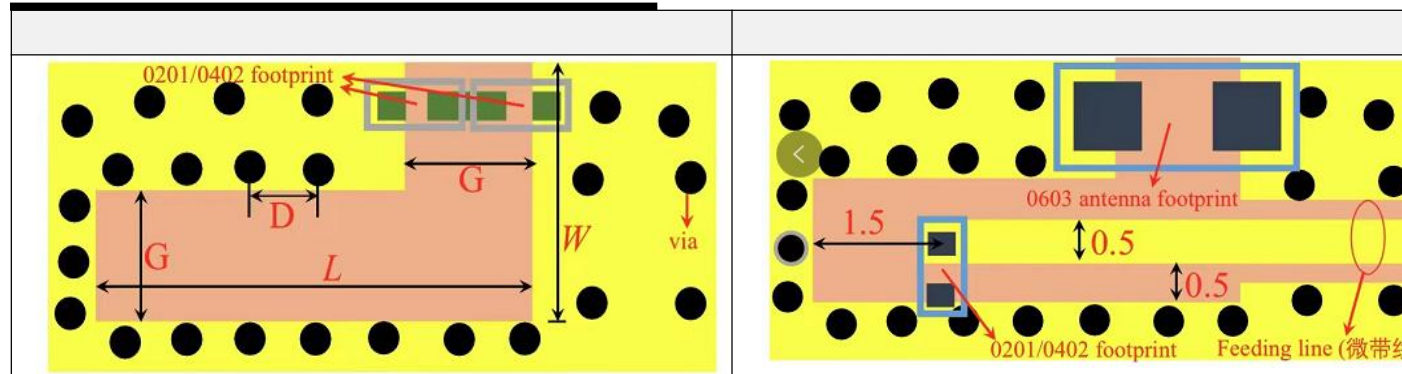
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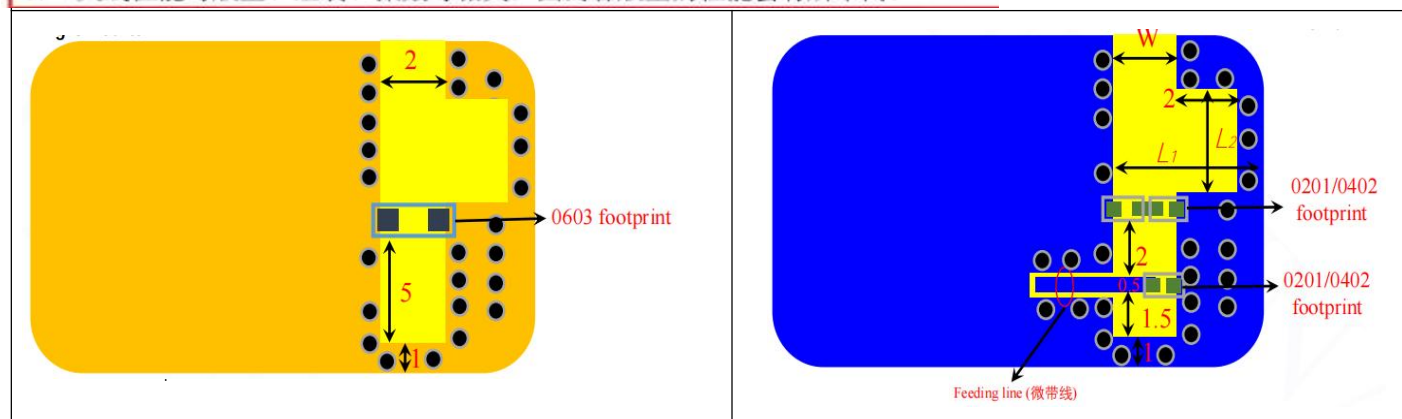


## Evaluation Board Reference



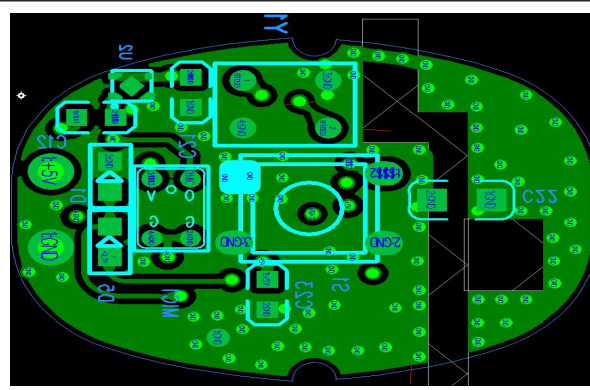
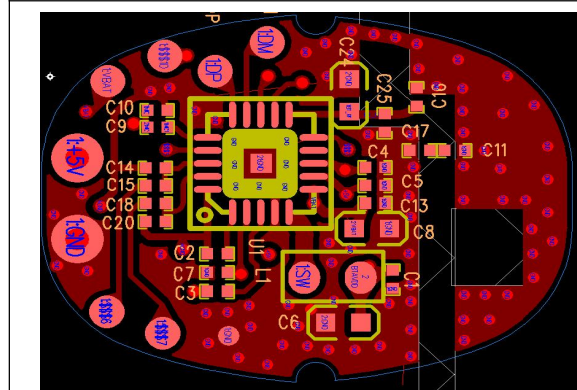
## 设计标准:

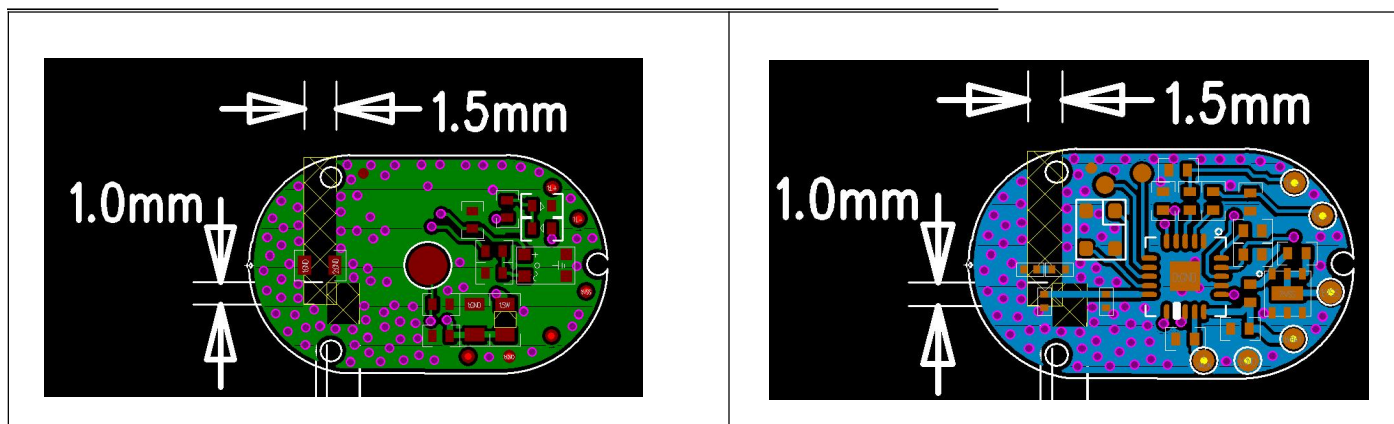
1. 图示中的尺寸为标准封装，仅作为参考；净空区的尺寸会根据每个版型进行调整和优化。
2. 天线最优放置于PCBA的中间区域；天线及其板后的匹配物料最优放置于板边缘。
3. 净空区周围需一排过孔，与PCBA上的其它回路或物料进行隔离。
4. G最优为1.5~2mm, W最优为3~5mm, L最优为4~6mm, D最优为0.5~1mm。
5. 天线性能与版型、组装、佩戴等相关，因而各版型的性能会有所不同。



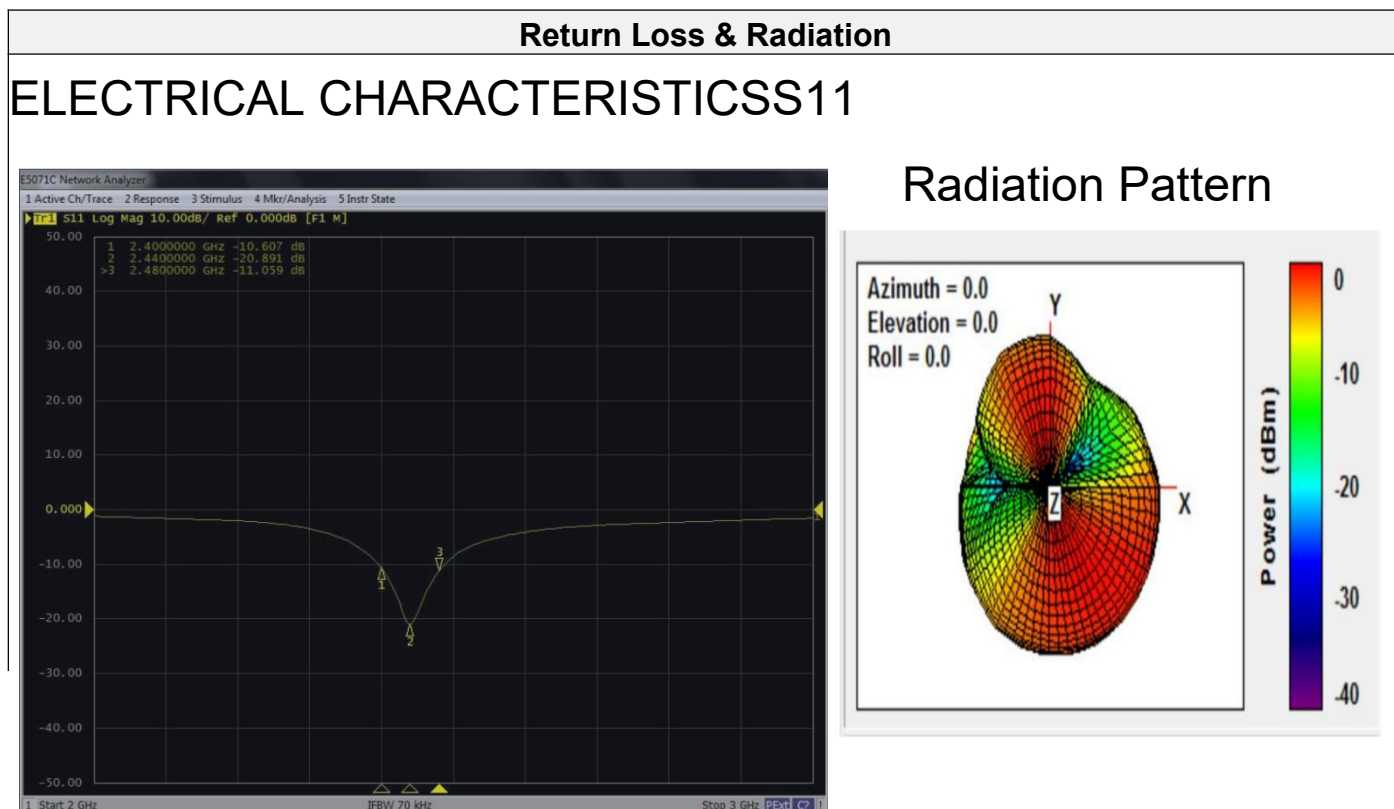
## 设计指导:

- 1、原则上，净空区左侧边缘距离板边的间距L1应该尽量大，且注意与底部电池的间距。
- 2、净空区的宽度W最优为1.5mm~2mm。
- 3、净空区的长度L2的长度为2mm~4mm。





## Electrical Characteristics



Radiation

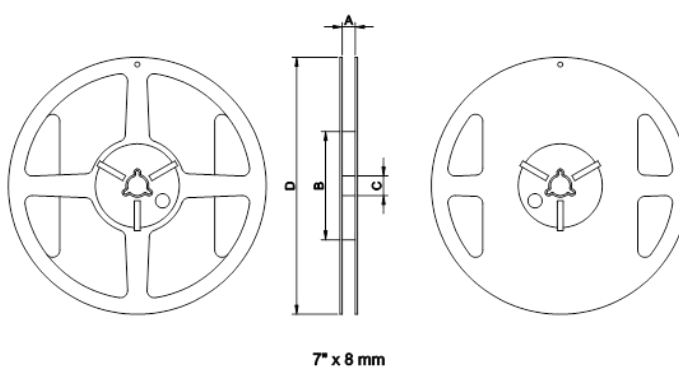
Electrical Characteristics

|   | Feature           | Specification   |
|---|-------------------|-----------------|
| 1 | Central frequency | 2445MHz         |
| 2 | Bandwidth         | >100MHz         |
| 3 | Peak gain         | >3dBi           |
| 4 | VSWR              | <2              |
| 5 | Polarization      | Linear          |
| 6 | Azimuth beamwidth | Omnidirectional |
| 7 | Impedance         | 50 Ω            |

## Taping Specifications

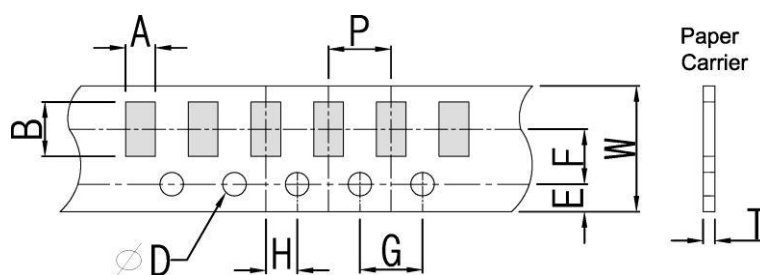
## Reel and Taping Specification

## Reel Specification



| TYPE | SIZE |         | A       | B     | C        | D     |
|------|------|---------|---------|-------|----------|-------|
| 1608 | 7"   | 4K/Reel | 4.0±0.5 | 4.0±2 | 13.5±0.5 | 178±2 |

## Tapping Specification



| Packaging  | Type | A         | B         | W        | E         | F        | G        | H        | T         | $\psi$ D  | P       |
|------------|------|-----------|-----------|----------|-----------|----------|----------|----------|-----------|-----------|---------|
| Paper Type | 1608 | 1.90±0.20 | 3.50±0.20 | 8.0±0.20 | 1.75±0.10 | 3.5±0.05 | 4.0±0.10 | 2.0±0.05 | 0.75±0.10 | 1.50±0.10 | 4.0±0.1 |

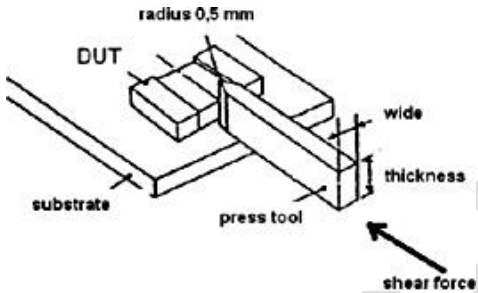
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### Reliability Table

| Test Item                                  | Procedure                                                                                                                                                                                                                                                                                                                                                | Requirements<br>Ceramic Type                                          | Remark<br>(Reference)     |
|--------------------------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------------------------------|---------------------------|
| <b>Electrical Characterization</b>         |                                                                                                                                                                                                                                                                                                                                                          | Fulfill the electrical specification                                  | User Spec.                |
| <b>Thermal Shock</b>                       | 1. Preconditioning:<br>$50 \pm 10^{\circ}\text{C}$ / 1 hr , then keep for $24 \pm 1$ hrs at room temp.<br>2. Initial measure: Spec: refer Initialspec.<br>3. Rapid change of temperature test:<br>$-30^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ ; 100 cycles;<br>15 minutes at Lower category temperature;<br>15 minutes at Upper category temperature. | No Visible Damage.<br>Fulfill the electrical specification.           | MIL-STD-202<br>107        |
| <b>Temperature Cycling</b>                 | 1. Initial measure: Spec: refer Initialspec.<br>2. 100 Cycles ( $-30^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ ), Soak Mode=1 (2 Cycle/hours).<br>3. Measurement at $24 \pm 2$ Hours after test condition.                                                                                                                                               | No Visible Damage.<br>Fulfill the electrical specification.           | JESD22<br>JA104           |
| <b>High Temperature Exposure</b>           | 1. Initial measure: Spec: refer Initialspec.<br>2. Unpowered; 500hours @ $T=+85^{\circ}\text{C}$ .<br>3. Measurement at $24 \pm 2$ hours after test.                                                                                                                                                                                                     | No Visible Damage.<br>Fulfill the electrical specification.           | MIL-STD-202<br>108        |
| <b>Low Temperature Storage</b>             | 1. Initial measure: Spec: refer Initialspec.<br>2. Unpowered: 500hours @ $T=-30^{\circ}\text{C}$ .<br>3. Measurement at $24 \pm 2$ hours after test.                                                                                                                                                                                                     | No Visible Damage.<br>Fulfill the electrical specification.           | MIL-STD-202<br>108        |
| <b>Solderability<br/>(SMD Bottom Side)</b> | Dipping method:<br>a. Temperature: $235 \pm 5^{\circ}\text{C}$<br>b. Dipping time: $3 \pm 0.5\text{s}$                                                                                                                                                                                                                                                   | The solder should cover over 95% of the critical area of bottom side. | IEC 60384-21/22<br>4.10   |
| <b>Soldering Heat Resistance<br/>(RSH)</b> | Preheating temperature: $150 \pm 10^{\circ}\text{C}$ .<br>Preheating time: 1~2 min.<br>Solder temperature: $260 \pm 5^{\circ}\text{C}$ .<br>Dipping time: $5 \pm 0.5\text{s}$                                                                                                                                                                            | No Visible Damage.                                                    | IEC 60384-21/22<br>4.10   |
| <b>Vibration</b>                           | 5g's for 20 min., 12 cycles each of 3 orientations<br>Note: Use 8"X5" PCB .031" thick 7 secure points on, one long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10-2000 Hz.                                                                                                           | No Visible Damage.                                                    | MIL-STD-202<br>Method 204 |
| <b>Mechanical Shock</b>                    | Three shocks in each direction shall be applied along the three mutually perpendicular axes of the test specimen (18 shocks)<br>Peak value: 1,500g's<br>Duration: 0.5ms<br>Velocity change: 15.4 ft/s<br>Waveform: Half-sine                                                                                                                             | No Visible Damage.                                                    | MIL-STD-202<br>Method 213 |
| <b>Humidity Bias</b>                       | 1. Humidity: 85% R.H., Temperature: $85 \pm 2^{\circ}\text{C}$ .<br>2. Time: $500 \pm 24$ hours.<br>3. Measurement at $24 \pm 2$ hrs after test condition.                                                                                                                                                                                               | No Visible Damage.<br>Fulfill the electrical specification.           | MIL-STD-202<br>Method 106 |

## 2.4GHz 3216 Chip Antenna: RANT1608F245C01

|                           |                                                                                                                                                                                        |                                                                                                                                                                          |              |
|---------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------------|
| <b>Board Flex (SMD)</b>   | 1. Mounting method:<br>IR-Reflow. PCB Size (L:100 × W:40 × T:1.6mm)<br>2. Apply the load in direction of the arrow until bending reaches 2 mm.                                         | No Visible Damage.                                                                                                                                                       | AEC-Q200 005 |
| <b>Adhesion</b>           | Force of 1.8Kg for 60 seconds.<br>                                                                    | No Visible Damage<br>Magnification of 20X or greater may be employed for inspection of the mechanical integrity of the device body terminals and body/terminal junction. | AEC-Q200 006 |
| <b>Physical Dimension</b> | Any applicable method using x10 magnification, micrometers, calipers, gauges, contour projectors, or other measuring equipment, capable of determining the actual specimen dimensions. | In accordance with specification.                                                                                                                                        | JESD22 JB100 |

### Revision History

| Revision | Date       | Content                         |
|----------|------------|---------------------------------|
| 1        | 2019/03/01 | New Datasheet                   |
| 2        | 2020/02/22 | Add 2D radiation characteristic |